

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7028565

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the ASSIGNEE ADVANCED MATERIAL TECHNOLOGIES, INC. previously recorded on Reel 057808 Frame 0445. Assignor(s) hereby confirms the CORRECT ASSIGNEES ARE ADVANCED MATERIAL TECHNOLOGIES, INC. AND MICROINNOVATORS LABORATORY, INC..

CONVEYING PARTY DATA

Name	Execution Date
ADVANCED MATERIAL TECHNOLOGIES, INC.	09/27/2021

RECEIVING PARTY DATA

Name:	ADVANCED MATERIAL TECHNOLOGIES, INC.
Street Address:	956-1 NISHIHIRAI
City:	NAGAREYAMA-SHI, CHIBA
State/Country:	JAPAN
Postal Code:	270-0156
Name:	MICROINNOVATORS LABORATORY, INC.
Street Address:	2-1-17 ASUTOPIA
City:	UBE-SHI, YAMAGUCHI
State/Country:	JAPAN
Postal Code:	755-0152

PROPERTY NUMBERS Total: 3

Property Type	Number
Patent Number:	9976219
Application Number:	15956185
Application Number:	16762212

CORRESPONDENCE DATA

Fax Number: (312)321-4299

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 312-321-4200

Email: ykawabata@crowell.com, usassignments@crowell.com

Correspondent Name: TADASHI HORIE/YUKIKO KAWABATA

Address Line 1: P.O. BOX 10395

Address Line 4: CHICAGO, ILLINOIS 60610

ATTORNEY DOCKET NUMBER:	099380.0000011
--------------------------------	----------------

PATENT

NAME OF SUBMITTER:	TADASHI HORIE
SIGNATURE:	/Tadashi Horie/
DATE SIGNED:	11/17/2021
Total Attachments: 7 source=OPM01278_US_Assignment Agreement#page1.tif source=OPM01278_US_Assignment Agreement#page2.tif source=OPM01278_US_Assignment Agreement#page3.tif source=OPM01278_US_Assignment Agreement#page4.tif source=CoverSheet#page1.tif source=Notice#page1.tif source=Notice#page2.tif	

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6971847

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ADVANCED MATERIAL TECHNOLOGIES, INC.	09/27/2021
RECEIVING PARTY DATA	
Name:	MICROINNOVATORS LABORATORY, INC.
Street Address:	2-1-17 ASUTOPIA,
Internal Address:	UBE-SHI
City:	YAMAGUCHI
State/Country:	JAPAN
Postal Code:	755-0152
PROPERTY NUMBERS Total: 3	
Property Type	Number
Patent Number:	9976219
Application Number:	15956185
Application Number:	16762212
CORRESPONDENCE DATA	
Fax Number:	(312)321-4299
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3123214200
Email:	usassignments@crowell.com, jdempsey@crowell.com
Correspondent Name:	TADASHI HORIE
Address Line 1:	CROWELL & MORING LLP
Address Line 2:	PO BOX 10395
Address Line 4:	CHICAGO, ILLINOIS 60611
ATTORNEY DOCKET NUMBER:	099380.0000011
NAME OF SUBMITTER:	TADASHI HORIE
SIGNATURE:	/Tadashi Horie/
DATE SIGNED:	10/15/2021
Total Attachments: 4	
source=OPM01278_US_Assignment Agreement#page1.tif	
source=OPM01278_US_Assignment Agreement#page2.tif	

ASSIGNMENT AGREEMENT

This ASSIGNMENT AGREEMENT (this "Assignment") is entered into on September 27, 2021 by and between Advanced Material Technologies, Inc., a corporation organized and existing under the laws of Japan, having a place of business at 956-1 Nishihirai, Nagareyama-shi, Chiba, 270-0156 Japan, ("Assignor"), and MicroInnovators Laboratory, Inc., a corporation organized and existing under the laws of Japan, having a place of business at 2-1-17 Asutopia, Ube-shi, Yamaguchi, 755-0152 Japan, ("Assignee") (each, a "party," and collectively, the "parties").

WHEREAS, Schedule A attached hereto identifies a United States Patent and United States Patent Applications owned by Assignor (the "Applications"); and

WHEREAS, Assignor has agreed to assign to both Assignor and Assignee, and Assignor and Assignee desire to receive from Assignor, all of Assignor's right, title and undivided interest in and to the Applications.

NOW, THEREFORE, in consideration of the premises and the mutual agreements and covenants hereinafter set forth, the parties hereto agree as follows:

1. Assignment (a) Assignor hereby irrevocably assigns, transfers, conveys and delivers to both Assignor and Assignee, and Assignor and Assignee hereby receive from Assignor, all of Assignor's right, title and undivided interest in and to the Applications for the United States, including, without limitation, the inventions and improvements described and claimed therein, all reissuances, revisions, divisionals, continuations, extensions, continuations-in-part and counterparts thereof and all corresponding rights that are or may be secured under the laws of the United States, now or hereafter arising or in effect, for Assignor's and Assignee's own use and enjoyment, and for the use and enjoyment of

Assignor's and Assignee's successors, assigns and other legal representatives, as fully and entirely as the same would have been held and enjoyed by Assignor if this Assignment had not been made, together with Assignor's all rights to collect royalties, products and proceeds in connection with any of the foregoing and Assignor's all rights to sue and recover damages or other relief for all past, present or future infringement, misappropriation or other violation of any of the foregoing, and all rights corresponding thereto.

(b) Assignor hereby requests the Commissioner of Patents and Trademarks in the United States Patent and Trademark Office to record Assignor and Assignee as the co-assignees of the Applications and to deliver to Assignor and Assignee, and to Assignor's and Assignee's attorneys, agents, successors or assigns, all official documents and communications as may be warranted by this Assignment.

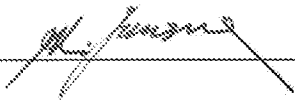
2. Further Action. Assignor and Assignee shall each take, and shall cause their respective Affiliates to take, any and all additional actions as may be necessary or appropriate to effect the transactions contemplated hereby, including, but not limited to, execution of individual assignment documentation for filing with the authorities of each individual country. The responsibility to file assignments with the national patent offices of each country shall be on Assignee and Assignee shall bear the cost of filing such assignments.

3. Counterparts. This Assignment may be executed and delivered (including by facsimile or other means of electronic transmission, such as by electronic mail in "pdf" form) in one or more counterparts, and by the different parties hereto in separate counterparts, each of which when executed shall be deemed to be an original, but all of which taken together shall constitute one and the same agreement.

4. Governing Law. This Assignment shall be governed by, and construed in accordance with, the Laws of Japan.

IN WITNESS THEREOF, the parties hereto have caused this Assignment to be executed as of the date written below by the officer thereunto duly authorized.

Advanced Material Technologies, Inc.

By  _____

Name Juichiro Yamaguchi

Title President & CEO

Date September 27, 2021

SCHEDULE A

Serial Number	Filing date	Patent Number	Title of the Invention
14/620,470	02/12/2015	9,976,219	ELECTRODE, FERROELECTRIC CERAMICS AND MANUFACTURING METHOD THEREOF
15/956,185	04/18/2018	pending	ELECTRODE, FERROELECTRIC CERAMICS AND MANUFACTURING METHOD THEREOF
16/762,212	05/07/2020	pending	FILM STRUCTURE AND METHOD FOR MANUFACTURING THE SAME